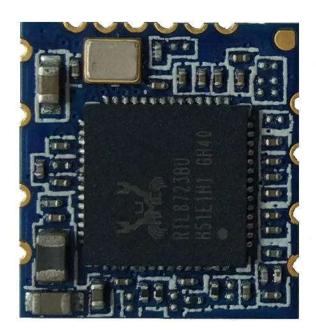


## RTL8723BU WIFI 蓝牙一体模块



USB 接口

#### 1. General Description

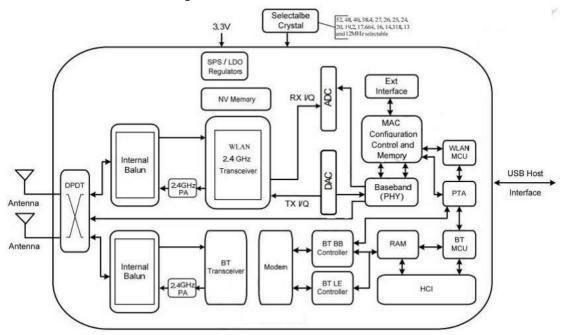
RTL8723BU is a highly integrated single-chip 802.11n Wireless LAN (WLAN) USB 2.0 Multi-Function network interface controller with integrated Bluetooth 2.1/3.0/4.0 controller. It combines a WLAN MAC, a 1T1R capable WLAN baseband, and RF in single chip. The RTL8723BU provides a complete solution for a high-performance integrated wireless and Bluetooth device. The integration provides better coordination between 802.11 and Bluetooth, and with sophisticated dynamic power control and packet traffic arbitration, RTL8723BU is able to provide the best coexistence performance Overview.

#### 2. The range of applying

MID, networking camera, STB, GPS, Desk-Top Pc; Note-book; TV; Blue-ray Disk; Set-top box, Hard disk player, Network Radios, PSP and other device which need be supported by wireless networking.



- 3. Product Specification
- 3.1 Function Block diagram





# 3.2 Electrical and Performance Specification

Item	Description
Product Name	RTL8723BU
Major Chipset	RTL8273BU

Host Interface	USB2.0					
Chandand	WiFi: EEE 802.11b, IEEE 802.11g, IEEE 802.11n					
Standard	B T: V2.1+EDR/BT v3.0/BT v3.0+HS/BT v4.0					
Frequency Range	2.4GHz~2.4835GHz					
	802.11b: CCK, DQPSK, DBPSK					
Modulation Type	802.11g: 64 QAM, 16 QAM, QPSK, BPSK					
Modulation Type	802.11n: 64 QAM, 16 QAM, QPSK, BPSK					
	B T: 8DPSK, π/4 DQPSK, GFSK					
Working Mode	Infrastructure, Ad-Hoc					
	Wifi: 802.11b: 11, 5.5, 2, 1 Mbps					
	802.11g: 54, 48, 36, 24, 18, 12, 9, 6 Mbps					
Data Transfer Rate	802.11n: MCS 0 to 7 for HT20MHz ;MCS 0 to 7 for					
Data Harister Nate	HT40MHz					
	B T: 1 Mbps for Basic Rate					
	2,3 Mbps for Enhanced Data Rate					
	IEEE 802.11b: DSSS (Direct Sequence Spread Spectrum)					
Spread Spectrum	IEEE 802.11g/n:OFDM (Orthogonal Frequency Division					
	Multiplexing)					
	BT: FHSS(Frequency-Hopping Spread Spectrum)					
	Wi Fi: 1M: -92dBm@8%PER					
	6M: -89dBm@10%PER					
Sensitivity @PER	11M:-86dBm@8%PER					
, C = 2.1	54M:-73dBm@10%PER					
	135M:-67dBm@10%PER					
	B T: -89dBm@1Mbps, -85dBm@2Mbps, -83dBm@3Mbps					
RF Power	16dBm@11b, 14dBm@11g, 13dBm@11n					
	BT: MAX +10dBm					
Antenna type	Connect to the external antenna through the half hole					
	WiFi: Indoor 100M, Outdoor 300M, according the local					
The transmit distance	environment					
	BT: 10m MAX.					
Product Dimension(L*W*H)	12.2*13*1.6mm (LxWxH) ;Tolerance: +-0.2mm					
Power supply	3.3V +/-0.3V					
Power Consumption	standby mode 96mA@3.3V ,					
	TX mode 255mA@3.3V					
Clock source	40MHz					
Working Temperature	0°C to +70°C					
Storage temperature	-55°C to +125°C					



### 3.3 DC Characteristic

Terms	Contents
Specification : IEEE80	02.11b

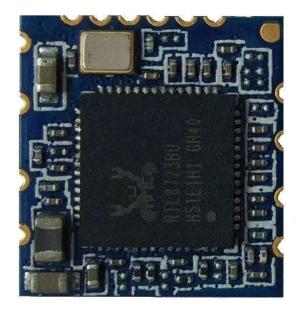
Mode	DSSS / CCK						
Frequency	2412 – 2484MHz						
Data rate	1, 2, 5.5, 11Mbps						
DC Characteristics	min	Тур.	max.	unit			
TX mode	225	235	255	mA			
Rx mode	134	135	135	mA			
Sleep mode	95	96	97	mA			
Specification : IEEE80	2.11g						
Mode	OFDM						
Frequency	2412 - 2484MHz						
Data rate	6, 9, 12, 18, 24, 36, 48,	6, 9, 12, 18, 24, 36, 48, 54Mbps					
DC Characteristics	min	Тур.	max.	unit			
TX mode	190	225	290	mA			
Rx mode	133	135	135	mA			
Sleep mode	95	96	97	mA			
Specification: IEEE80	2.11n						
Mode	OFDM						
Frequency	2412 - 2484MHz						
Data rate	6.5, 13, 19.5, 26, 39, 52	2, 58.5, 65Mbps					
DC Characteristics	min	Тур.	max.	unit			
TX mode	185	245	287	mA			
Rx mode	133	134	135	mA			
Sleep mode	95	96	97	mA			

### 3.4 RF Characteristic

Mode Ra	Rate(Mbps)	Power(dBm)				EVM(dB)	Sensitivity(dBm)			
Wiode	Kate(IVIDPS)	CH1	CH7	CH13	CH1	CH7	CH13	CH1	CH7	CH13
116	1	16.9	16.7	16.84	-24.23	-23.88	-23.69	-92	-92	-92
11b	11	17.2	16.95	16.89	-23.4	-24.13	-23.59	-85	-85	-85
11-	6	14.5	14.26	14.35	-28.7	-28.96	-28.54	-86	-86	-86
11g	54	14.2	14.13	14.69	-28.4	-28.58	-29.5	-71	-71	-71
11n	MCS0	13.6	13.5	13.7	-28.7	-29.3	-28.6	-84	-84	-84
HT20	MCS7	13.7	13.5	13.6	-28.3	-28.5	-29.2	-66	-66	-66
11n	MCS0	13.8	13.9	13.4	-28.4	-28.9	-29.5	-85	-85	-85
HT40	MCS7	13.2	13.5	13.8	-28.7	-29.5	-28.5	-66	-66	-66

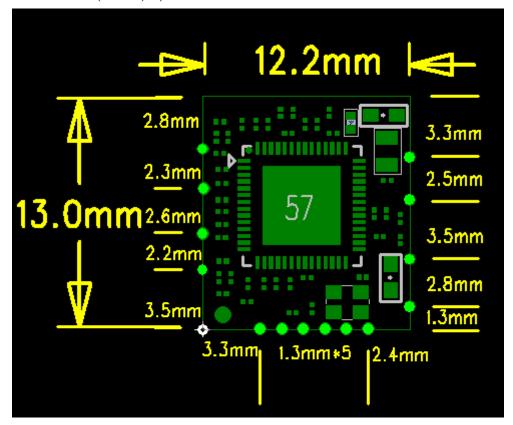


## 3.5 Product Photo



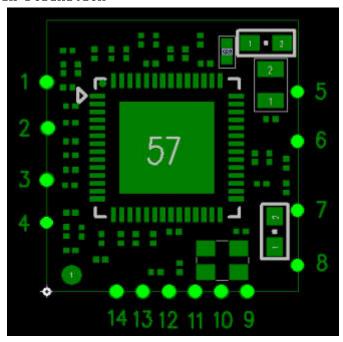
### 3.6 Mechanical Specification

12.2\*13\*1.6mm (LxWxH) ;Tolerance: +-0.2mm





## 3.7 Product Pin Definition



Pin No:	Function	Description
1	GND	Ground
2	RF0	WLAN/BT RF TX/RX signal0
3	RF1	WLAN/BT RF TX/RX signal port 1
4	XIN	40MHz crystal reference clock input
5	GND	Ground
6	D+	High-Speed USB D+ Signal
7	D-	High-Speed USB D- Signal
8	VCC33	VDD3.3V for Digital IO
9	SUSPEND	device wake host
10	WO_WLAN	host wake device
11	BT_PCM_CLK	PCM clock
12	BT_PCM_SYNC	PCM sync
13	BT_PCM_OUT	PCM output
14	BT_PCM_IN	PCM input

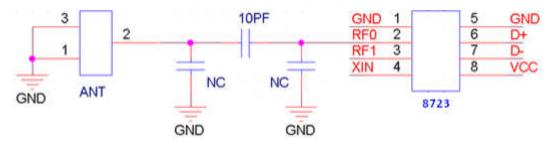
# 4. Supported platform

Operating System	CPU Framework	Driver
WIN2000/XP/VISTA/WIN7/WIN8	X86 Platform	Enable
LINUX2.4/2.6	ARM, MIPSII	Enable



### 5. Peripheral Schematic Reference Design

WiFi RF Circuit reference pictures



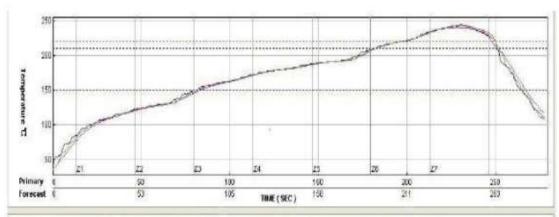
### Note:

- 1. Pls reserve a "pi" circuit for antenna matching.
- 2. The RF circuit needs to keep 50  $\Omega$  impedance.
- 3. The USB differential pair needs to keep 90  $\,\Omega$  impedance.
- 4. Keep RF1 and XIN NC, WiFi and BT use same antenna RF0.

### 6. Package Information



### 7. Typical Solder Reflow Profile



Tix.	RA	MP	SOAP Betwee	n 150 to 210 TC	Refle	w 228°C	Peak Terre	perwine TC	
2	1,4	-7%	99.4	20%	50.6	39%	243.1	62%	
3	1.4	-4%	1005	35%	54.6	15%	241.0	20%	
14	1.4	-5%	101.4	38%	54.4	48	244.7	814.	
Different in Temp	0.04		1.99		2.52	1	3.65		
P.2	1.4	-7%	99.4	21%	52.6	2%	2431	12%	
P.3	1,4	-4%	1005	35%	58.5	19%	241.0	20%	
P.4	1.6	-5%	101.4	38%	54.4	44%	244.7	93%	
Different in Temp	0.04		1.98		2.92		3.66		



### 8. Precautions for use

- 1. Pls handle the module under ESD protection.
- 2. Reflow soldering shall be done according to the solder reflow profile. Peak temperature  $245\,^{\circ}$  C.
- 3. Products require baking before mounting if humidity indicator cards reads >30% temp <30 degree C, humidity < 70% RH, over 96 hours. Baking condition: 125 degree C, 12 hours Baking times: 1 time
- 4. Storage Condition: Moisture barrier bag must be stored under 30 degree C, humidity under 85% RH. The calculated shelf life for the dry packed product shall be a 12 months from the bag seal date. Humidity indicator cards must be blue, <30%.